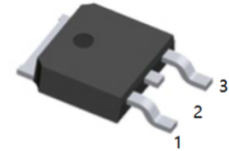


## Features

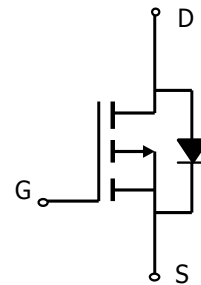
- $V_{DS} (V) = -40V$
- $I_D = -40A$
- $R_{DS(ON)} < 22m\Omega$  ( $V_{GS} = -10V$ )
- $R_{DS(ON)} < 29m\Omega$  ( $V_{GS} = -4.5V$ )



1.G 2.D 3.S  
TO-252(DPAK) top view

## General Description

The AOD4189 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. With the excellent thermal resistance of the TO-252 package, this device is well suited for high current load applications.



### Absolute Maximum Ratings $T_C=25^\circ C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>B,H</sup>	$I_D$	$T_C=25^\circ C$	A
		$T_C=100^\circ C$	
Pulsed Drain Current <sup>C</sup>	$I_{DM}$	-50	A
Avalanche Current <sup>C</sup>	$I_{AR}$	-35	A
Repetitive avalanche energy $L=0.1mH^C$	$E_{AR}$	61	mJ
Power Dissipation <sup>B</sup>	$P_D$	$T_C=25^\circ C$	W
		$T_C=100^\circ C$	
Power Dissipation <sup>A</sup>	$P_{DSM}$	$T_A=25^\circ C$	W
		$T_A=70^\circ C$	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 175	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A,G</sup>	$R_{\theta JA}$	15	20	$^\circ C/W$
$t \leq 10s$				
Maximum Junction-to-Ambient <sup>A,G</sup>	$R_{\theta JA}$	41	50	$^\circ C/W$
Steady-State				
Maximum Junction-to-Case <sup>D,F</sup>	$R_{\theta JC}$	2	2.4	$^\circ C/W$

### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
B <sub>V</sub> DSS	Drain-Source Breakdown Voltage	I <sub>D</sub> =-250μA, V <sub>GS</sub> =0V	-40			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-40V, V <sub>GS</sub> =0V T <sub>J</sub> =55°C			-1 -5	μA
I <sub>GSS</sub>	Gate-Body leakage current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =-250μA	-1.7	-1.9	-3	V
I <sub>D(ON)</sub>	On state drain current	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-5V	-50			A
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =-10V, I <sub>D</sub> =-12A V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-8A		18 23	22 29	mΩ
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =-5V, I <sub>D</sub> =-12A		35		S
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =-1A, V <sub>GS</sub> =0V		-0.74	-1	V
I <sub>S</sub>	Maximum Body-Diode Continuous Current				-20	A
<b>DYNAMIC PARAMETERS</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =-20V, f=1MHz		1870		pF
C <sub>oss</sub>	Output Capacitance			185		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			155		pF
R <sub>g</sub>	Gate resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	2.5	4.5	6.5	Ω
<b>SWITCHING PARAMETERS</b>						
Q <sub>g</sub> (-10V)	Total Gate Charge	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-20V, I <sub>D</sub> =-12A		31.4	41	nC
Q <sub>g</sub> (-4.5V)	Total Gate Charge			7.9	10	
Q <sub>gs</sub>	Gate Source Charge			7.6		nC
Q <sub>gd</sub>	Gate Drain Charge			6.2		nC
t <sub>D(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-20V, R <sub>L</sub> =1.6Ω, R <sub>GEN</sub> =3Ω		10		ns
t <sub>r</sub>	Turn-On Rise Time			18		ns
t <sub>D(off)</sub>	Turn-Off DelayTime			38		ns
t <sub>f</sub>	Turn-Off Fall Time			24		ns
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =-12A, dI/dt=100A/μs		32	42	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge	I <sub>F</sub> =-12A, dI/dt=100A/μs		30		nC

A: The value of R<sub>θJA</sub> is measured with the device in a still air environment with T<sub>A</sub>=25°C. The power dissipation P<sub>DSM</sub> and current rating I<sub>DSM</sub> are based on T<sub>J(MAX)</sub>=150°C, using steady state junction-to-ambient thermal resistance.

B: The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=175°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=175°C.

D: The R<sub>θJA</sub> is the sum of the thermal impedance from junction to case R<sub>θJC</sub> and case to ambient.

E: The static characteristics in Figures 1 to 6 are obtained using t ≤ 300 μs pulses, duty cycle 0.5% max.

F: These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of T<sub>J(MAX)</sub>=175°C. The SOA curve provides a single pulse rating.

G: These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C.

H: The maximum current rating is limited by bond-wires.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

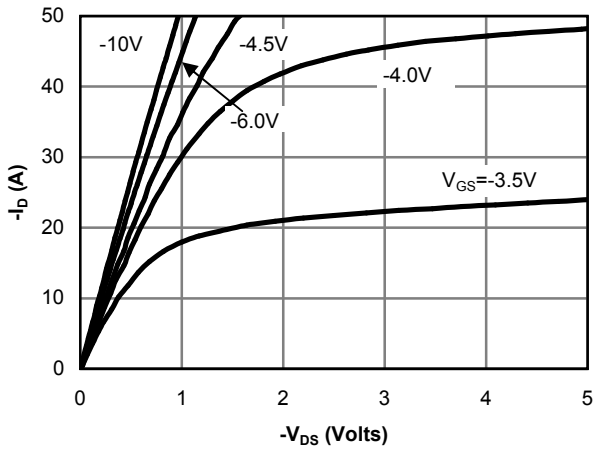


Figure 1: On-Region Characteristics

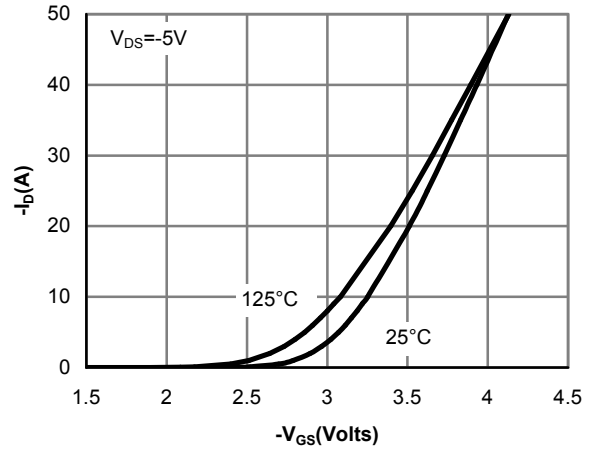


Figure 2: Transfer Characteristics

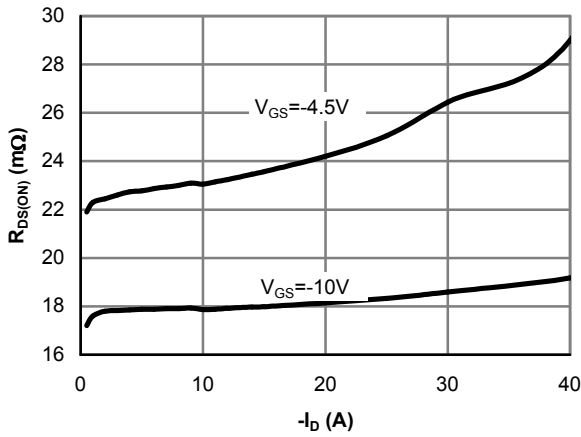


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

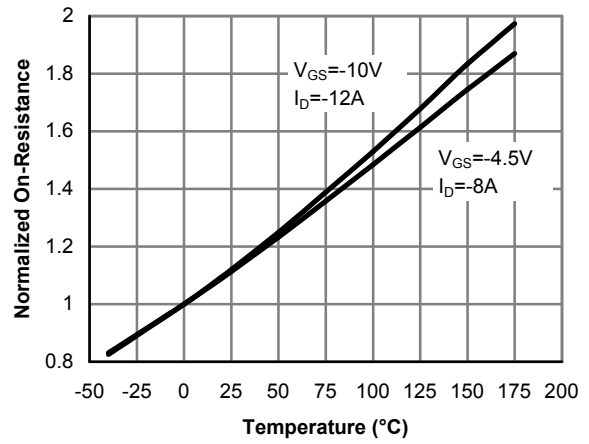


Figure 4: On-Resistance vs. Junction Temperature

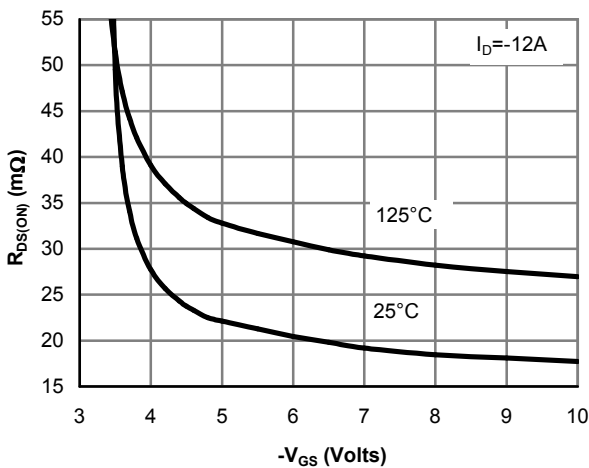


Figure 5: On-Resistance vs. Gate-Source Voltage

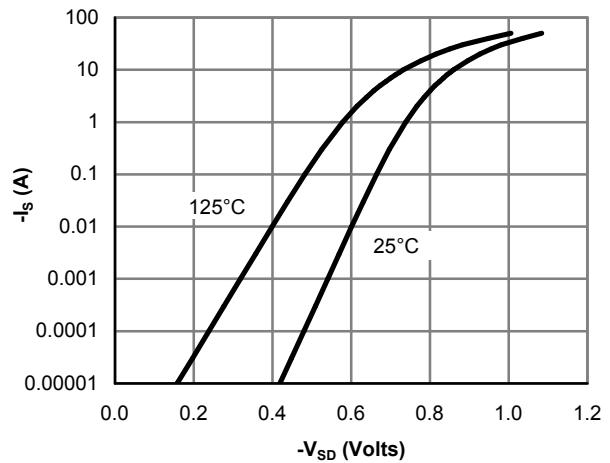


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

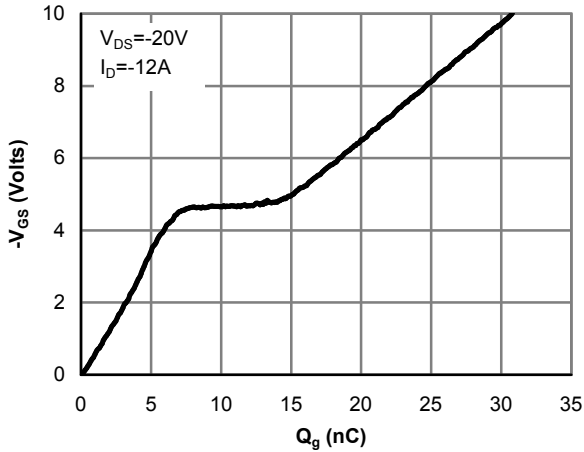


Figure 7: Gate-Charge Characteristics

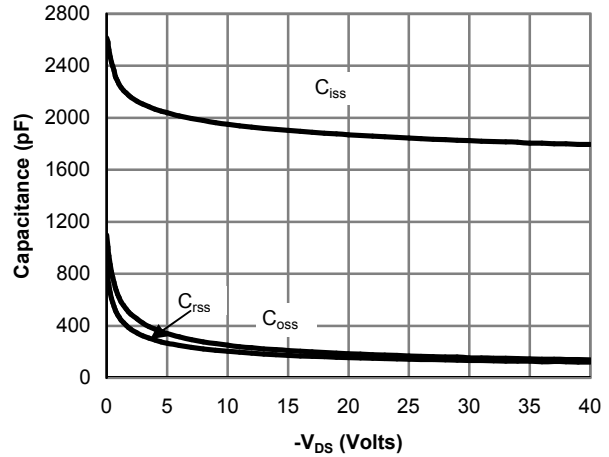


Figure 8: Capacitance Characteristics

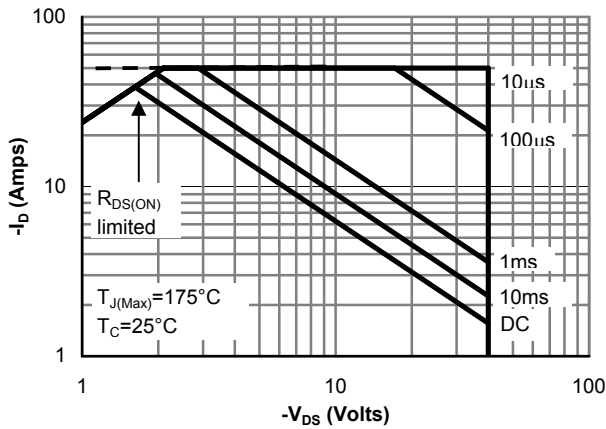


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

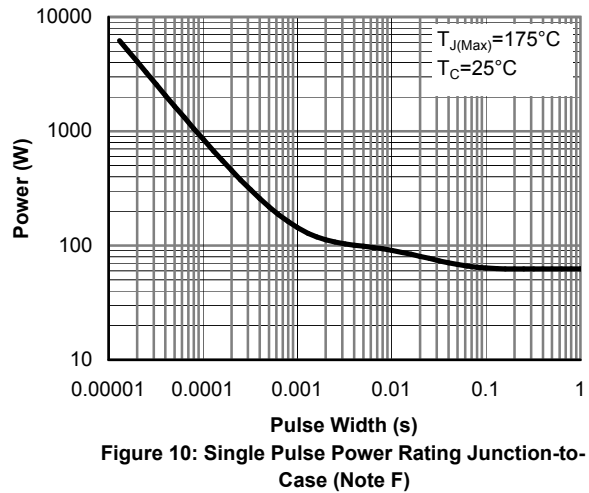


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

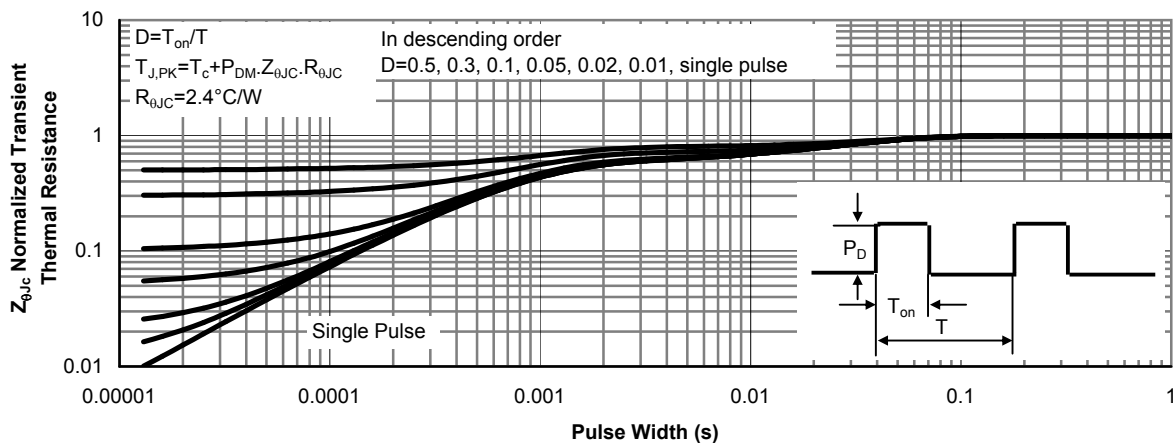


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

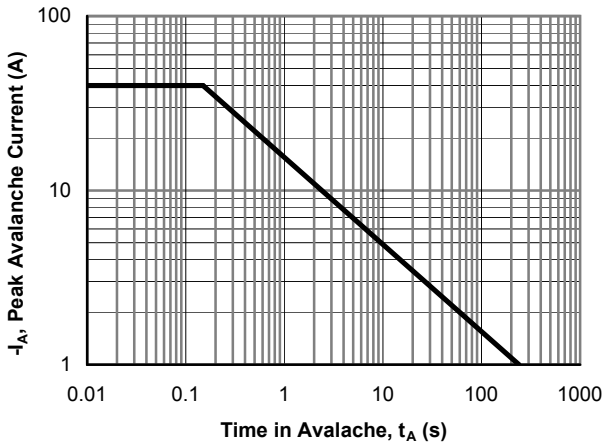


Figure 12: Single Pulse Avalanche Capability

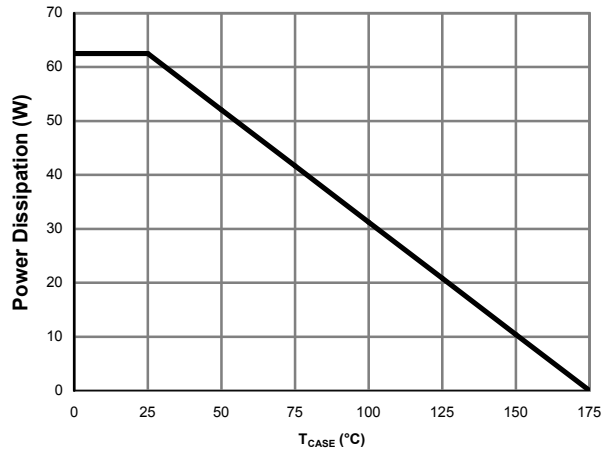


Figure 13: Power De-rating (Note B)

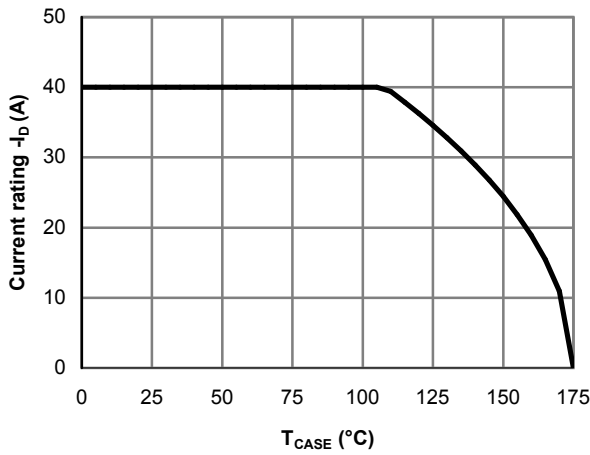


Figure 14: Current De-rating (Note B)

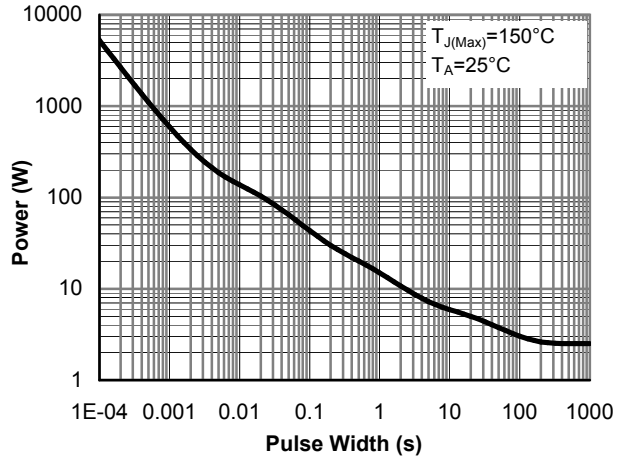


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note G)

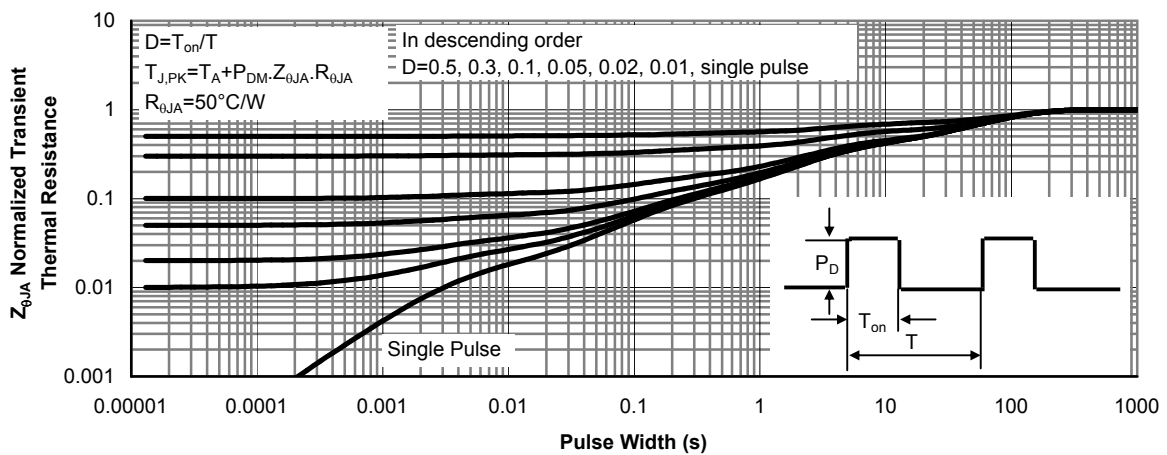
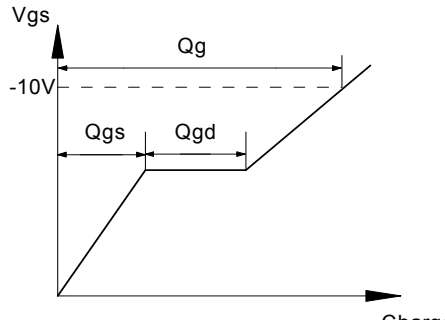
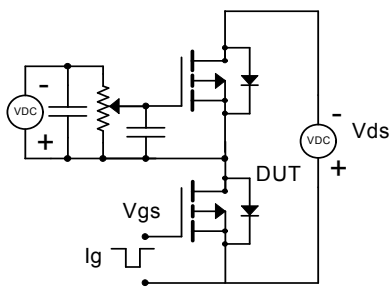
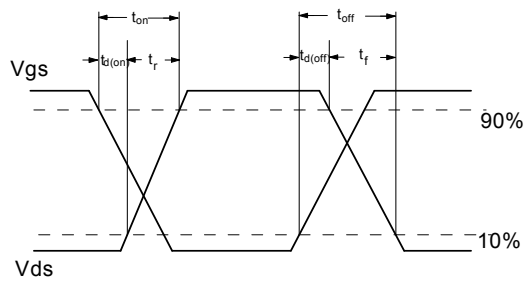
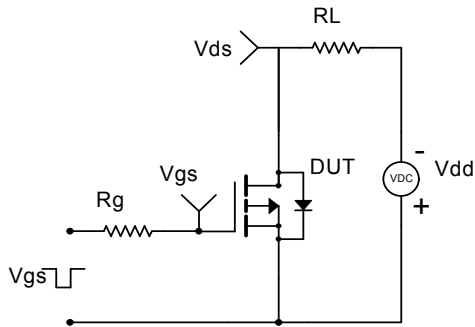


Figure 16: Normalized Maximum Transient Thermal Impedance (Note G)

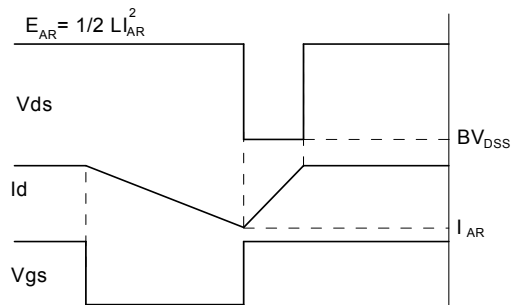
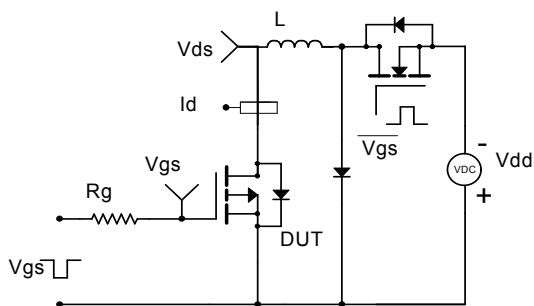
Gate Charge Test Circuit & Waveform



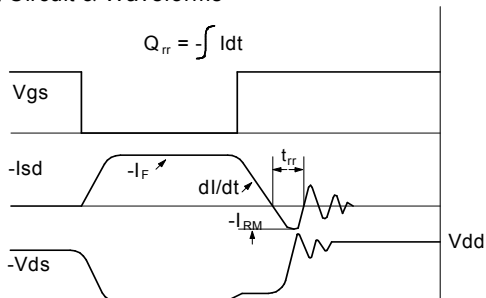
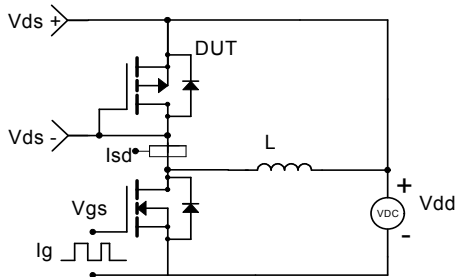
Resistive Switching Test Circuit & Waveforms



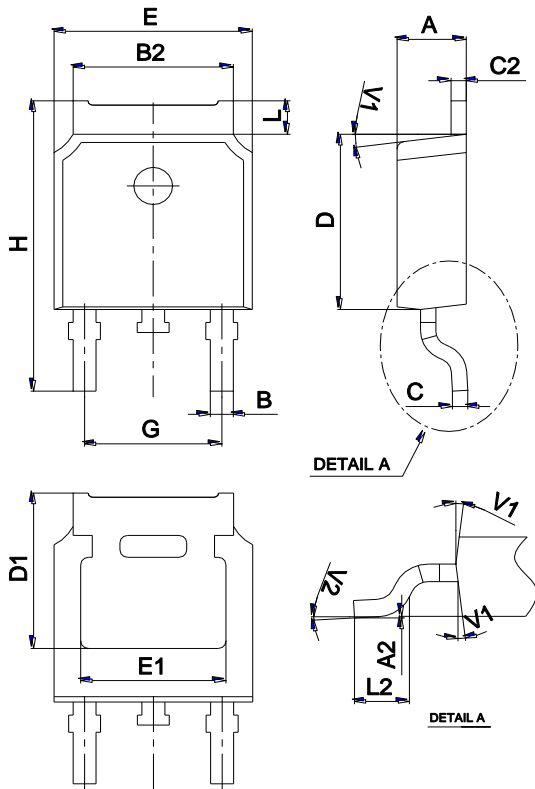
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

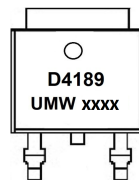


Package Mechanical Data TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
UMW AOD4189	TO-252	2500	Tape and reel